

## UMF Equipment – Rapid Thermal Processor

### AccuThermo AW410

The Rapid Thermal Process System is an instrument which heats wafers to high temperatures on a timescale of several minutes or less. Such rapid heating rates are attained by high intensity lamps process. RTP is used for a wide variety of applications in semiconductor manufacturing including ion implant activation, polysilicon annealing, dopant activation, thermal oxidation and metal reflow.

- Features:
- Substrate size: Up to 4" diameter
  - Temp. range: Room temp. to ~1150°C
  - Ramp up rate: > 50°C /sec
  - Gas lines: N<sub>2</sub>, O<sub>2</sub>, Ar
  - Temperature/ Time control: Temperature measuring precision  $\leq \pm 2^\circ\text{C}$

Please refer to supplier information page: <https://allwin21.com/> for further details of the system.

For any inquiry, please contact Dr. Terence Wong (Tel: 3400 2075; Email: [tai-lun.wong@polyu.edu.hk](mailto:tai-lun.wong@polyu.edu.hk)).



Rapid Thermal Processor



Process Monitor Screen